

RoHS

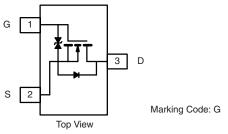
COMPLIANT

Vishay Siliconix

N-Channel 1.5-V (G-S) MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	R_{DS(on)} (Ω)	I _D (mA)			
20	5 at V _{GS} = 4.5 V	200			
	7 at V _{GS} = 2.5 V	175			
	9 at V _{GS} = 1.8 V	150			
	10 at V _{GS} = 1.5 V	50			

SC-75A or SC-89



Ordering Information:

Si1032R-T1-E3 (SC-75A, Lead (Pb)-free) Si1032R-T1-GE3 (SC-75A, Lead (Pb)-free and Halogen-free) Si1032X-T1-E3 (SC-89, Lead (Pb)-free) Si1032X-T1-GE3 (SC-89, Lead (Pb)-free and Halogen-free)

FEATURES

- Halogen-free Option Available
- Low-Side Switching
- Low On-Resistance: 5 Ω
- Low Threshold: 0.9 V (typ.)
- Fast Switching Speed: 35 ns
- TrenchFET[®] Power MOSFETs: 1.5-V Rated
- 2000 V ESD Protection

BENEFITS

- Ease in Driving Switches
- Low Offset (Error) Voltage
- Low-Voltage Operation
- High-Speed Circuits
- Low Battery Voltage Operation

APPLICATIONS

- Drivers: Relays, Solenoids, Lamps, Hammers, Displays, Memories
- Battery Operated Systems
- Power Supply Converter Circuits
- · Load/Power Switching Cell Phones, Pagers

ABSOLUTE MAXIMUM RATINGS $T_A = 25 \text{ °C}$, unless otherwise noted								
			Si1032R		Si1032X			
Parameter		Symbol	5 s	Steady State	5 s	Steady State	Unit	
Drain-Source Voltage	V _{DS}	20				v		
Gate-Source Voltage		V _{GS}	± 6					
	T _A = 25 °C	I _D	200	140	210	200		
Continuous Drain Current (T _J = 150 °C) ^a	T _A = 85 °C		110	100	150	140		
Pulsed Drain Current ^a		I _{DM}	500		600		mA	
Continuous Source Current (Diode Conduct	tion) ^a	۱ _S	250	200	300 240			
	T _A = 25 °C	PD	280	250	340	300	mW	
Maximum Power Dissipation ^a for SC-75	T _A = 85 °C	۲D	145	130	170	150		
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150				°C	
Gate-Source ESD Rating (HBM, Method 3015)		ESD	2000				V	

Notes:

a. Surface Mounted on FR4 board.

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SPECIFICATIONS $T_A = 25 \text{ °C}$, unless otherwise noted								
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit		
Static				•				
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$	0.40	0.7	1.2	V		
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 2.8 V$		± 0.5	± 1.0	μA		
		$V_{DS} = 0 V, V_{GS} = \pm 4.5 V$		± 1.0	± 3.0			
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = 20 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$			1			
		V_{DS} = 20 V, V_{GS} = 0 V, T_{J} = 55 °C			10			
On-State Drain Current ^a	I _{D(on)}	$V_{DS} = 5 V, V_{GS} = 4.5 V$	250			mA		
	R _{DS(on)} -	$V_{GS} = 4.5 \text{ V}, I_D = 200 \text{ mA}$			5	- Ω		
		V _{GS} = 2.5 V, I _D = 175 mA			7			
Drain-Source On-State Resistance ^a		V _{GS} = 1.8 V, I _D = 150 mA			9			
		V _{GS} = 1.5 V, I _D = 40 mA			10			
Forward Transconductance ^a	9 _{fs}	$V_{DS} = 10 \text{ V}, \text{ I}_{D} = 200 \text{ mA}$		0.5		S		
Diode Forward Voltage ^a	V _{SD}	I _S = 150 mA, V _{GS} = 0 V			1.2	V		
Dynamic ^b	<u> </u>		1	<u>.</u>				
Total Gate Charge	Qg			750				
Gate-Source Charge	Q _{gs}	V_{DS} = 10 V, V_{GS} = 4.5 V, I_D = 250 mA		75		рС		
	<u> </u>					1		

Gate-Source Charge	Q _{gs}	V_{DS} = 10 V, V_{GS} = 4.5 V, I_{D} = 250 mA	75		рС
Gate-Drain Charge	Q _{gd}		225		
Turn-On Delay Time	t _{d(on)}			50	
Rise Time	t _r	V_{DD} = 10 V, R_L = 47 Ω		25	n 0
Turn-Off Delay Time	t _{d(off)}	$\text{I}_\text{D}\cong$ 200 mA, V_GEN = 4.5 V, R_G = 10 Ω		50	ns
Fall Time	t _f			25	

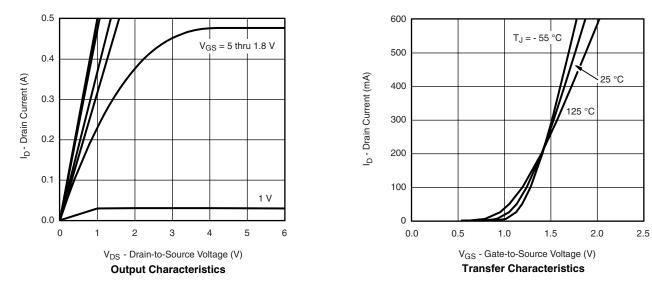
Notes:

a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.

b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

TYPICAL CHARACTERISTICS $T_A = 25 \text{ °C}$, unless otherwise noted

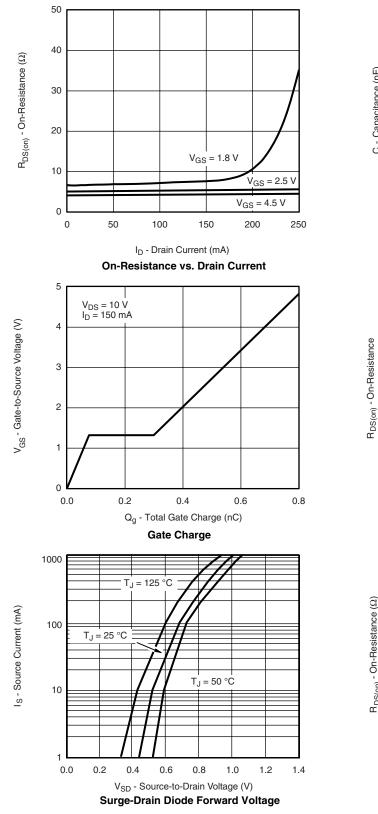


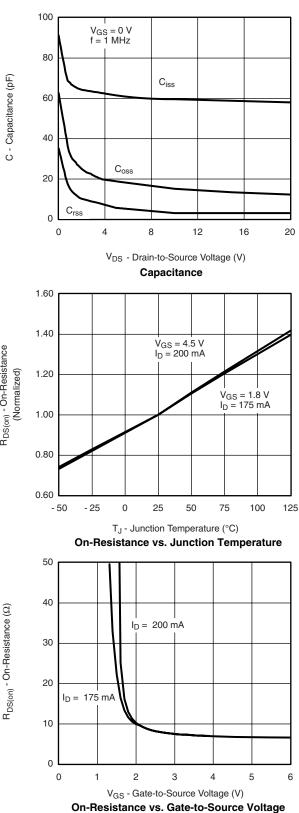


Si1032R/X

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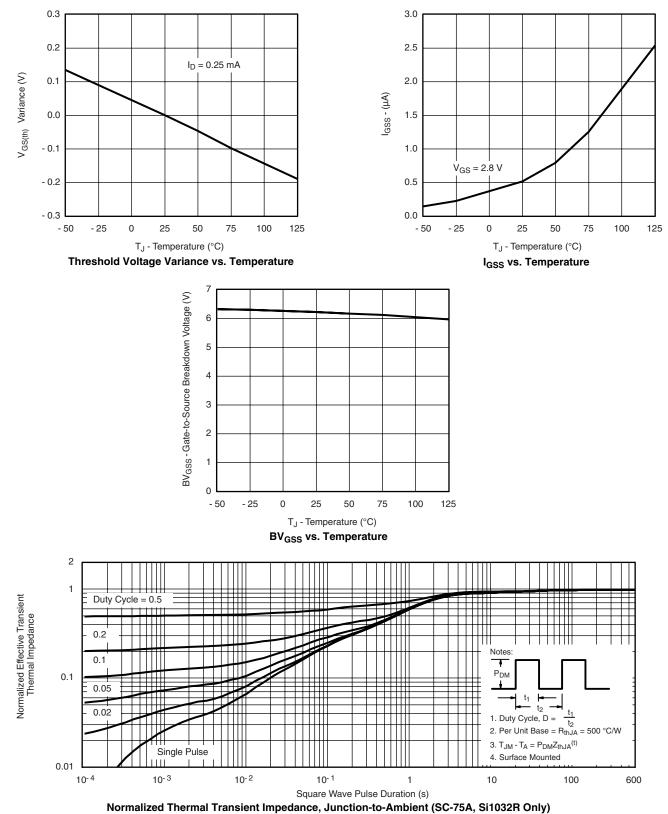




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Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see http://www.vishay.com/ppg?71172.





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